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*Genc, Y.; Sauer, F.; Wenzel, F.; Tuceryan, M.; Navab, N.;*

Augmented Reality, 2000. (ISAR 2000). Proceedings. IEEE and ACM International Symposium on , 5-6 Oct. 2000

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[Abstract] [PDF Full-Text (888 KB)] IEEE CNF

## 2 Practical solutions for calibration of optical see-through devices

*Genc, Y.; Tuceryan, M.; Navab, N.;*

Mixed and Augmented Reality, 2002. ISMAR 2002. Proceedings. International Symposium on , 30 Sept.-1 Oct. 2002

Pages:169 - 175

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### 3 Single point active alignment method (SPAAM) for optical see-through HMD calibration for AR

*Tuceryan, M.; Navab, N.;*

Augmented Reality, 2000. (ISAR 2000). Proceedings. IEEE and ACM International Symposium on , 5-6 Oct. 2000

**Pages:149 - 158**

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#### 4 A tracker alignment framework for augmented reality

*Baillot, Y.; Julier, S.J.; Brown, D.; Livingston, M.A.:*

Mixed and Augmented Reality, 2003. Proceedings. The Second IEEE and ACM International Symposium on , 7-10 Oct. 2003